ISO9001:2000 Certified SCI Quality System

Sierra Components, Inc.

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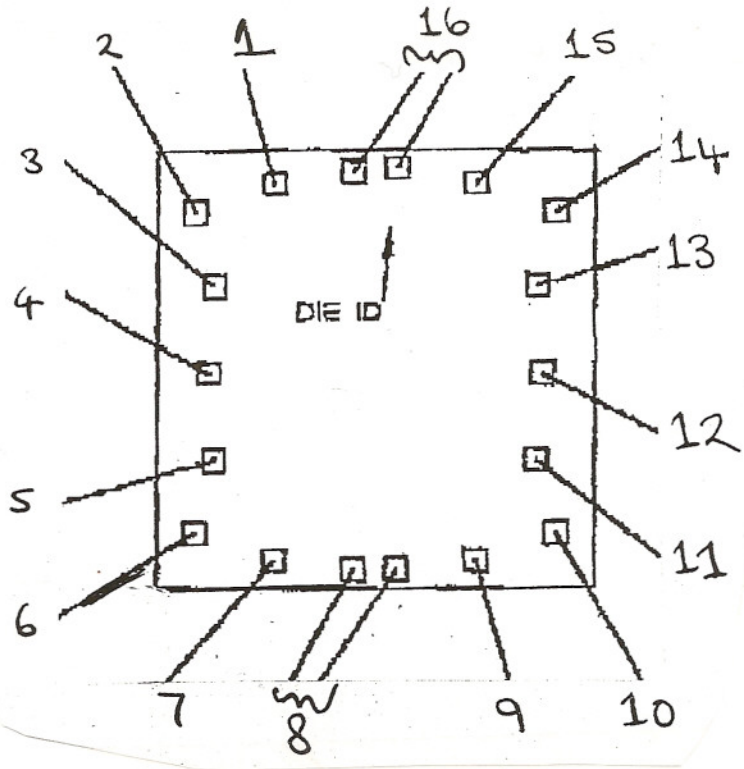
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



Pad	Function	Pad	Function
1	INPUT A1	9	INPUT D1
2	INPUT A2	10	INPUT D2
3	OUTPUT A	11	OUTPUT D
4	ENABLE	12	ENABLE
5	OUTPUT C	13	OUTPUT B
6	INPUT C2	14	INPUT B2
7	INPUT C1	15	INPUT B1
8	GND	16	VCC

NOTE: CHIP BACK MUST BE CONNECTED TO GND.

Topside Metal: Al
Backside: Si
Backside Potential: Ground
Mask Ref:
Bond Pads (Mils): 4 x 4

APPROVED BY:	**DIE SIZE (Mils): 79 x 78**	**DATE: 4/15/99**
MFG: National	**THICKNESS: 15**	**P/N: DS26C32**